

MBRD1035CTL

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	35	V
Average Rectified Forward Current (At Rated V_R , $T_C = 115^\circ\text{C}$)	I_O	5.0 10	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 20 kHz, $T_C = 115^\circ\text{C}$)	I_{FRM}	10	A
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I_{FSM}	50	A
Storage / Operating Case Temperature	T_{stg}, T_c	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature (Note 1)	T_J	-55 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R , $T_J = 25^\circ\text{C}$)	dv/dt	10,000	V/ μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	Per Leg	$R_{\theta JC}$	3.0	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (Note 2)	Per Leg	$R_{\theta JA}$	137	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3) (See Figure 2) $I_F = 5$ Amps, $T_J = 25^\circ\text{C}$ $I_F = 5$ Amps, $T_J = 100^\circ\text{C}$ $I_F = 10$ Amps, $T_J = 25^\circ\text{C}$ $I_F = 10$ Amps, $T_J = 100^\circ\text{C}$	Per Leg	V_F	0.47 0.41 0.56 0.55	V
Maximum Instantaneous Reverse Current (Note 3) (See Figure 4) $(V_R = 35$ V, $T_J = 25^\circ\text{C})$ $(V_R = 35$ V, $T_J = 100^\circ\text{C})$ $(V_R = 17.5$ V, $T_J = 25^\circ\text{C})$ $(V_R = 17.5$ V, $T_J = 100^\circ\text{C})$	Per Leg	I_R	2.0 30 0.20 5.0	mA

2. Rating applies when using minimum pad size, FR4 PC Board

3. Pulse Test: Pulse Width $\leq 250 \mu\text{s}$, Duty Cycle $\leq 2.0\%$

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRD1035CTL	DPAK	75 Units / Rail
MBRD1035CTLG	DPAK (Pb-Free)	75 Units / Rail
MBRD1035CTLT4	DPAK	2500 Units / Tape & Reel
MBRD1035CTLT4G	DPAK (Pb-Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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TYPICAL CHARACTERISTICS

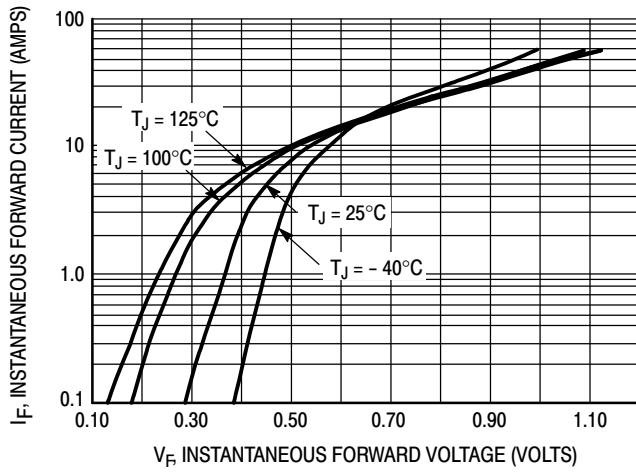


Figure 1. Typical Forward Voltage Per Leg

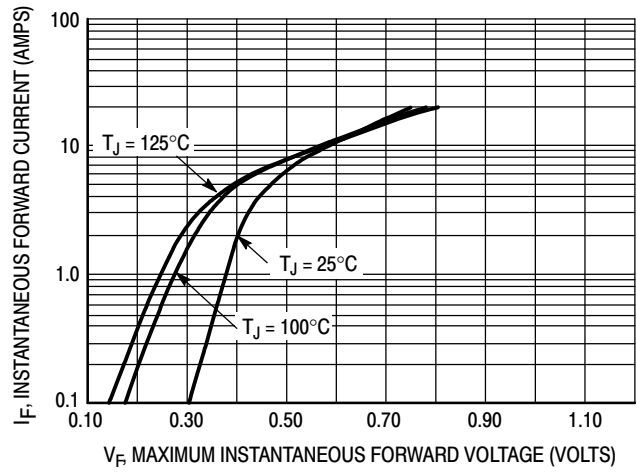


Figure 2. Maximum Forward Voltage Per Leg

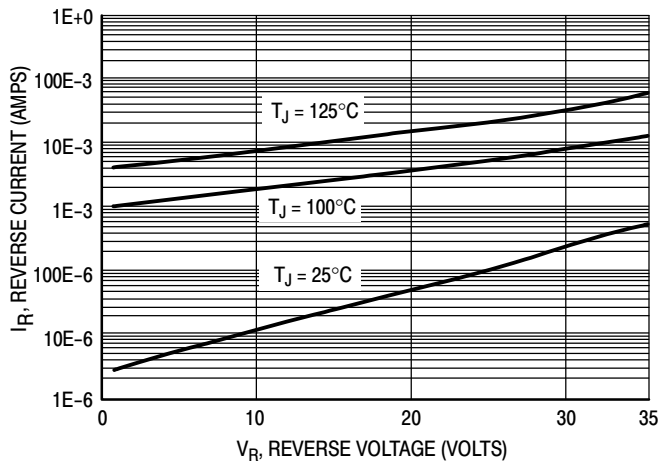


Figure 3. Typical Reverse Current Per Leg

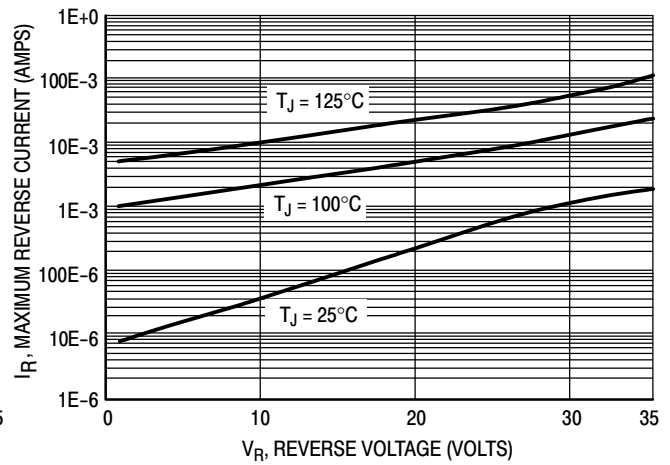


Figure 4. Maximum Reverse Current Per Leg

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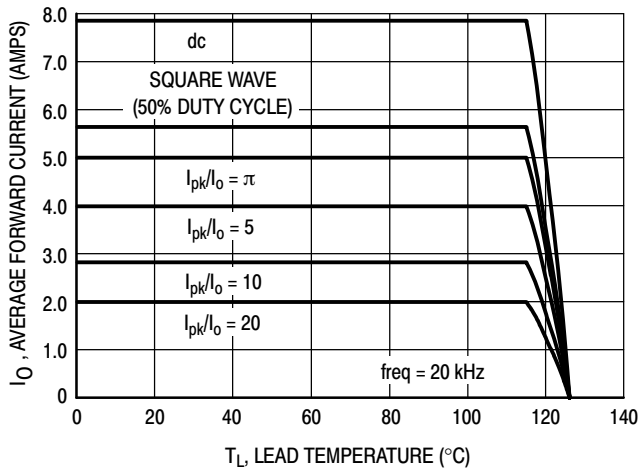


Figure 5. Current Derating Per Leg

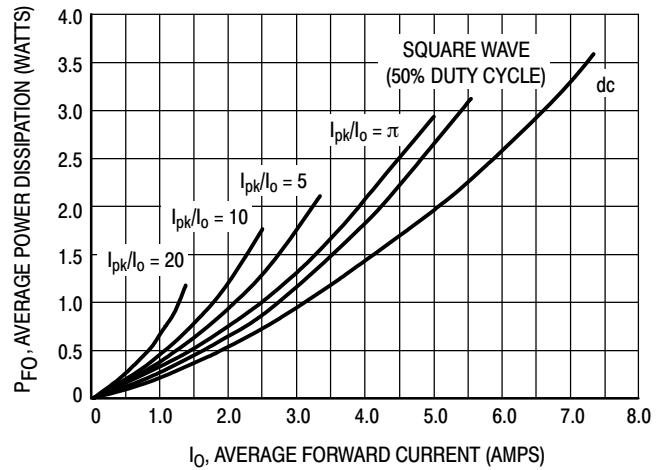


Figure 6. Forward Power Dissipation Per Leg

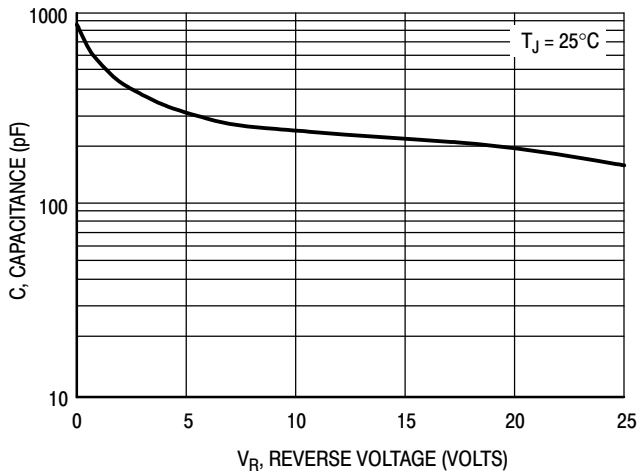


Figure 7. Capacitance Per Leg

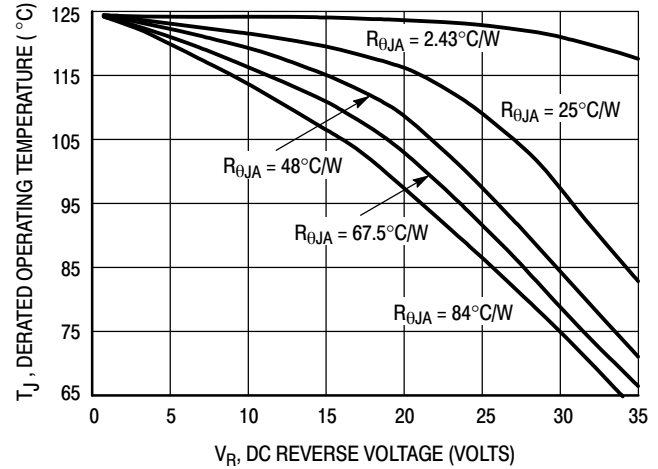


Figure 8. Typical Operating Temperature Derating Per Leg *

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$ = thermal impedance under given conditions,
 P_f = forward power dissipation, and
 P_r = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)P_r$, where $r(t) = R_{thja}$. For other power applications further calculations must be performed.

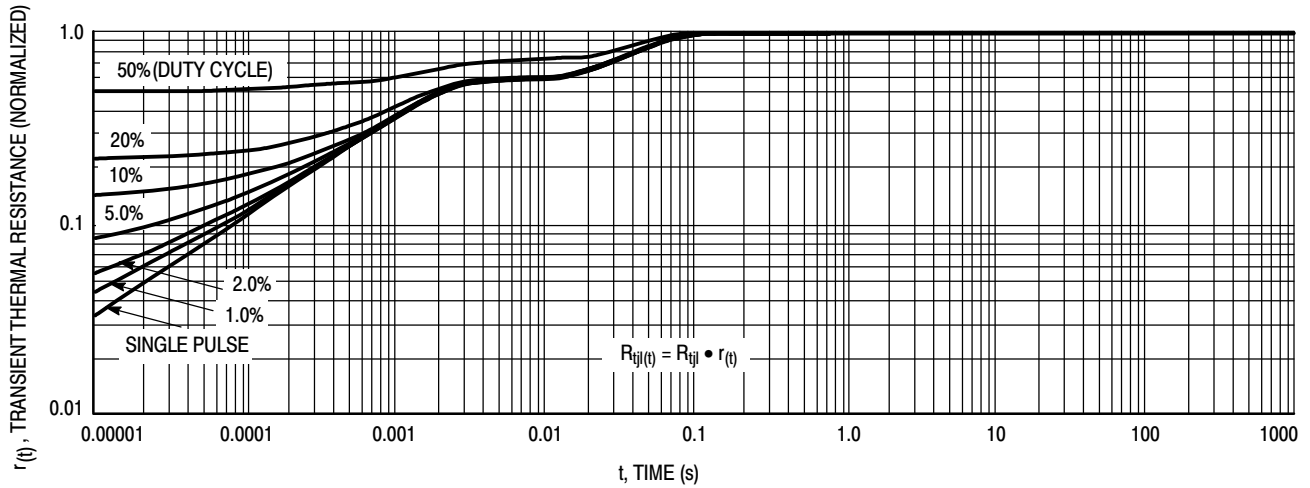


Figure 9. Thermal Response Junction to Case (Per Leg)

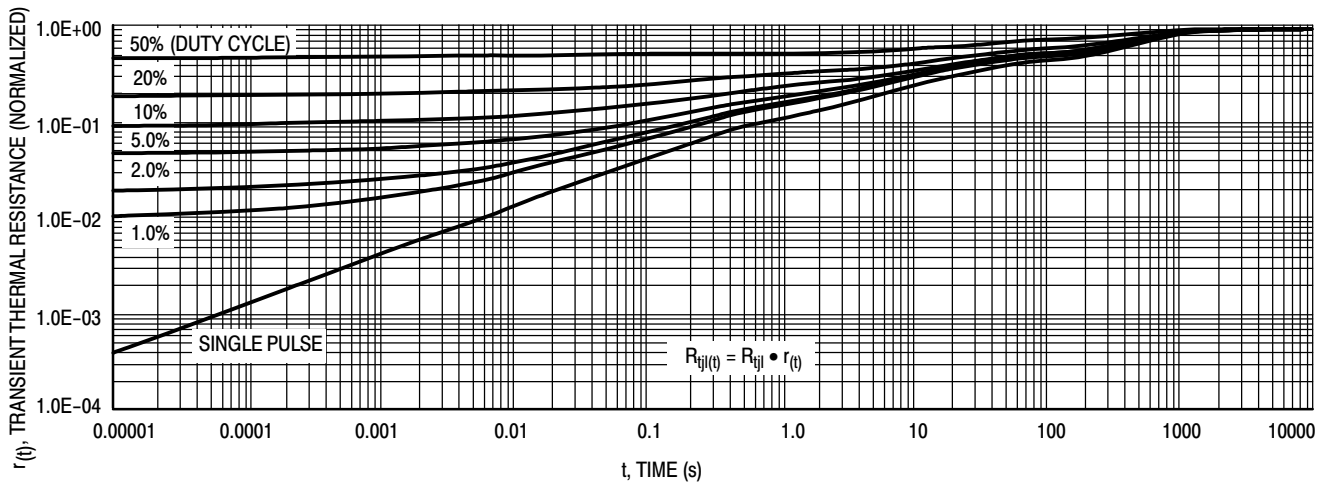


Figure 10. Thermal Response Junction to Ambient (Per Leg)

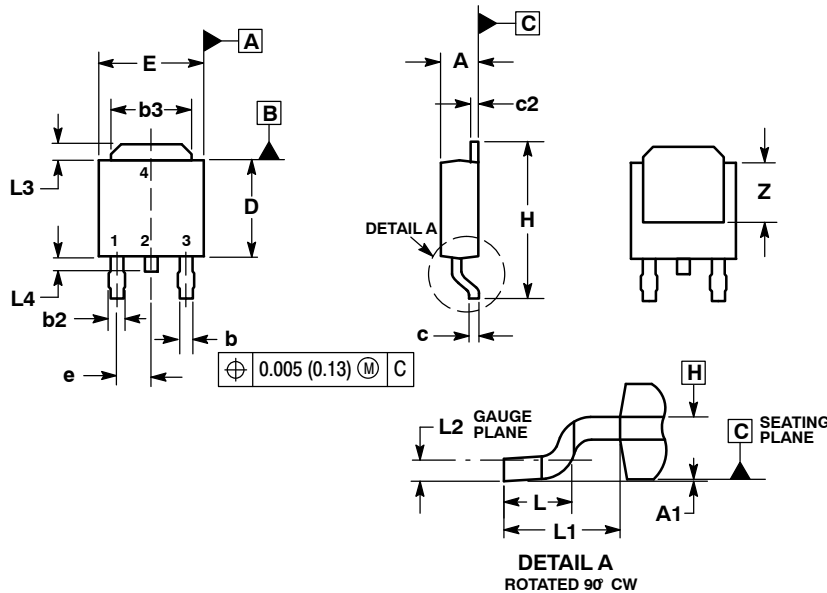
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PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C-01

ISSUE D

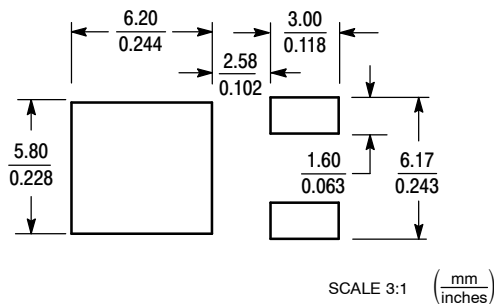


NOTES:


1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108	REF	2.74	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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